

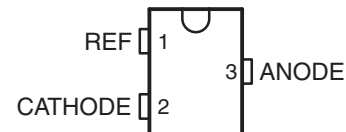
ADJUSTABLE PRECISION SHUNT REGULATORS

Check for Samples: [TL432A-Q1](#), [TL432B-Q1](#)

FEATURES

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results:
 - Device Temperature Grade 1: –40°C to 125°C Ambient Operating Temperature Range
 - Device HBM ESD Classification Level H2
 - Device CDM ESD Classification Level C3B
- Operation From –40°C to 125°C
- Reference Voltage Tolerance at 25°C
 - 0.5%...B Grade
 - 1%...A Grade
- Typical Temperature Drift...14 mV
- Low Output Noise
- Typical Output Impedance...0.2 Ω
- Sink Current Capability...1 mA to 100 mA
- Adjustable Output Voltage... V_{ref} to 36 V

DBZ (SOT-23-3) PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The TL432x-Q1 devices are three-terminal adjustable shunt regulators with specified thermal stability over the automotive temperature range. The output voltage can be set to any value between V_{ref} (approximately 2.5 V) and 36 V with two external resistors (see [Figure 17](#)). These devices have a typical output impedance of 0.2 Ω . Active output circuitry provides a very sharp turn-on characteristic, making these devices excellent replacements for Zener diodes in many applications such as onboard regulation, adjustable power supplies, and switching power supplies.

The TL432x-Q1 devices are offered in two grades with initial tolerances (at 25°C) of 0.5% and 1%, for the B and A grade, respectively. In addition, low output drift vs temperature ensures good stability over the entire temperature range.

The devices are characterized for operation from –40°C to 125°C.

ORDERING INFORMATION⁽¹⁾

T_A	V_{ref} TOLERANCE ($T_A = 25^\circ\text{C}$)	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	A Grade: 1%	SOT23 – DBZ	Reel of 3000	TL432AQDBZRQ1	TOIQ
	B Grade: 0.5 %			TL432BQDBZRQ1	TOHQ

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

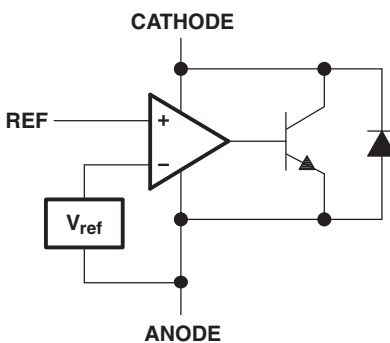


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

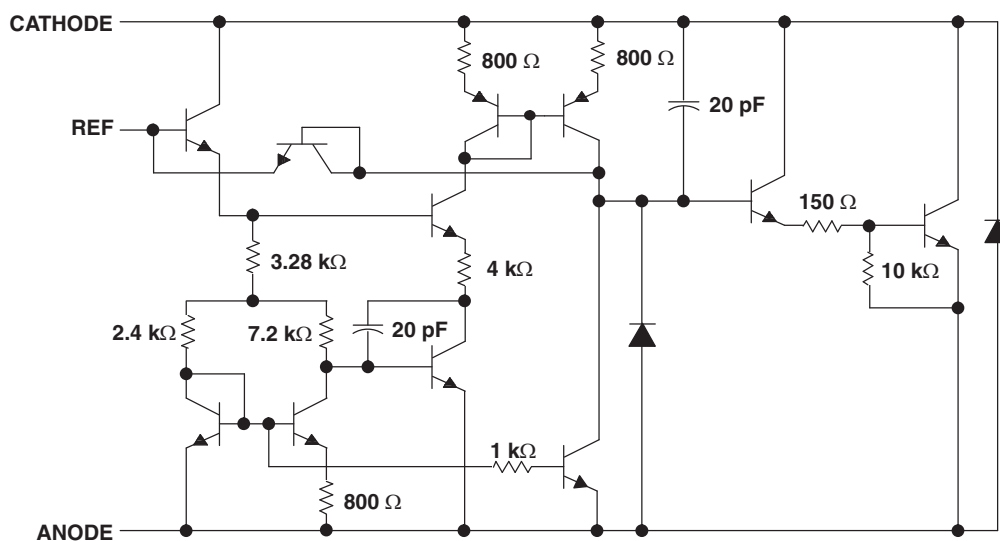
SYMBOL



FUNCTIONAL BLOCK DIAGRAM



EQUIVALENT SCHEMATIC



NOTE: All component values are nominal.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

V_{KA}	Cathode voltage ⁽²⁾	37 V
I_{KA}	Continuous cathode current range	–100 mA to 150 mA
	Reference input current range	–50 μ A to 10 mA
T_J	Operating virtual-junction temperature	150°C
T_{stg}	Storage temperature range	–65°C to 150°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Voltage values are with respect to the ANODE terminal, unless otherwise noted.

PACKAGE THERMAL DATA

PACKAGE	BOARD	θ_{JC}	θ_{JA}
SOT-23-3 (DBZ)	High K, JESD 51-7	76°C/W	206°C/W

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V_{KA}	Cathode voltage	V_{ref}	36	V
I_{KA}	Cathode current	1	100	mA
T_A	Operating free-air temperature	–40	125	°C
ESD Ratings	Human-body model (HBM) AEC-Q100 classification level H2		2	kV
	Charged-device model (CDM) AEC-Q100 classification level C3B		750	V

TL432A-Q1 ELECTRICAL CHARACTERISTICS

over recommended operating conditions, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CIRCUIT	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{ref} Reference voltage	Figure 2	$V_{KA} = V_{\text{ref}}, I_{KA} = 10\text{ mA}$	2470	2495	2520	mV
$V_{I(\text{dev})}$ Deviation of reference voltage over full temperature range (see Figure 1)	Figure 2	$V_{KA} = V_{\text{ref}}, I_{KA} = 10\text{ mA}, T_A = -40^\circ\text{C to } 125^\circ\text{C}$		14	34	mV
$\frac{\Delta V_{\text{ref}}}{\Delta V_{KA}}$ Ratio of change in reference voltage to the change in cathode voltage	Figure 3	$I_{KA} = 10\text{ mA}$		-1.4	-2.7	mV/V
		$\Delta V_{KA} = 10\text{ V} - V_{\text{ref}}$ $\Delta V_{KA} = 36\text{ V} - 10\text{ V}$		-1	-2	
I_{ref} Reference current	Figure 3	$I_{KA} = 10\text{ mA}, R1 = 10\text{ k}\Omega, R2 = \infty$		2	4	μA
$I_{I(\text{dev})}$ Deviation of reference current over full temperature range (see Figure 1)	Figure 3	$I_{KA} = 10\text{ mA}, R1 = 10\text{ k}\Omega, R2 = \infty, T_A = -40^\circ\text{C to } 125^\circ\text{C}$		0.8	2.5	μA
I_{min} Minimum cathode current for regulation	Figure 2	$V_{KA} = V_{\text{ref}}$		0.4	0.7	mA
I_{off} Off-state cathode current	Figure 4	$V_{KA} = 36\text{ V}, V_{\text{ref}} = 0$		0.1	0.5	μA
$ Z_{KA} $ Dynamic impedance (see Figure 1)	Figure 2	$I_{KA} = 1\text{ mA to } 100\text{ mA}, V_{KA} = V_{\text{ref}}, f \leq 1\text{ kHz}$		0.2	0.5	Ω

TL432B-Q1 ELECTRICAL CHARACTERISTICS

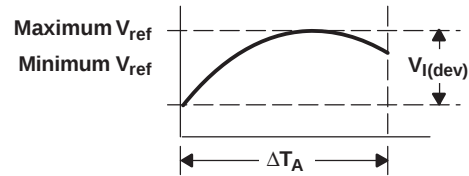
over recommended operating conditions, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CIRCUIT	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{ref} Reference voltage	Figure 2	$V_{KA} = V_{\text{ref}}, I_{KA} = 10\text{ mA}$	2483	2495	2507	mV
$V_{I(\text{dev})}$ Deviation of reference voltage over full temperature range (see Figure 1)	Figure 2	$V_{KA} = V_{\text{ref}}, I_{KA} = 10\text{ mA}, T_A = -40^\circ\text{C to } 125^\circ\text{C}$		14	34	mV
$\frac{\Delta V_{\text{ref}}}{\Delta V_{KA}}$ Ratio of change in reference voltage to the change in cathode voltage	Figure 3	$I_{KA} = 10\text{ mA}$		-1.4	-2.7	mV/V
		$\Delta V_{KA} = 10\text{ V} - V_{\text{ref}}$ $\Delta V_{KA} = 36\text{ V} - 10\text{ V}$		-1	-2	
I_{ref} Reference current	Figure 3	$I_{KA} = 10\text{ mA}, R1 = 10\text{ k}\Omega, R2 = \infty$		2	4	μA
$I_{I(\text{dev})}$ Deviation of reference current over full temperature range (see Figure 1)	Figure 3	$I_{KA} = 10\text{ mA}, R1 = 10\text{ k}\Omega, R2 = \infty, T_A = -40^\circ\text{C to } 125^\circ\text{C}$		0.8	2.5	μA
I_{min} Minimum cathode current for regulation	Figure 2	$V_{KA} = V_{\text{ref}}$		0.4	0.7	mA
I_{off} Off-state cathode current	Figure 4	$V_{KA} = 36\text{ V}, V_{\text{ref}} = 0$		0.1	0.5	μA
$ Z_{KA} $ Dynamic impedance (see Figure 1)	Figure 2	$I_{KA} = 1\text{ mA to } 100\text{ mA}, V_{KA} = V_{\text{ref}}, f \leq 1\text{ kHz}$		0.2	0.5	Ω

Deviation Parameters

The deviation parameters $V_{\text{ref(dev)}}$ and $I_{\text{ref(dev)}}$ are defined as the differences between the maximum and minimum values obtained over the recommended temperature range. The average full-range temperature coefficient of the reference voltage, $\alpha_{V_{\text{ref}}}$, is defined as:

$$|\alpha_{V_{\text{ref}}}| \left(\frac{\text{ppm}}{^{\circ}\text{C}} \right) = \frac{\left(\frac{V_{\text{I(dev)}}}{V_{\text{ref at } 25^{\circ}\text{C}}} \right) \times 10^6}{\Delta T_A}$$



where:

ΔT_A is the recommended operating free-air temperature range of the device.

$\alpha_{V_{\text{ref}}}$ can be positive or negative, depending on whether minimum V_{ref} or maximum V_{ref} , respectively, occurs at the lower temperature.

Example: $V_{\text{ref}} = 2495 \text{ mV}$ at 25°C , $V_{\text{I(dev)}} = 14 \text{ mV}$, $\Delta T_A = 165^{\circ}\text{C}$ for TL432B

$$|\alpha_{V_{\text{ref}}}| = \frac{\left(\frac{14 \text{ mV}}{2495 \text{ mV}} \right) \times 10^6}{165^{\circ}\text{C}} \approx 34 \frac{\text{ppm}}{^{\circ}\text{C}}$$

Because minimum V_{ref} occurs at the lower temperature, the coefficient is positive.

Dynamic Impedance

The dynamic impedance is defined as: $|z_{\text{KA}}| = \frac{\Delta V_{\text{KA}}}{\Delta I_{\text{KA}}}$

When the device is operating with two external resistors (see Figure 3), the total dynamic impedance of the circuit is given by:

$$|z'| = \frac{\Delta V}{\Delta I} \approx |z_{\text{KA}}| \left(1 + \frac{R_1}{R_2} \right)$$

Figure 1. Calculating Deviation Parameters and Dynamic Impedance

PARAMETER MEASUREMENT INFORMATION

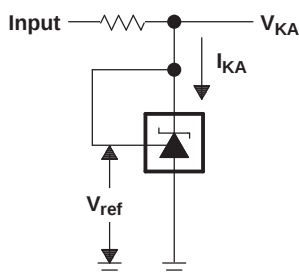


Figure 2. Test Circuit for $V_{KA} = V_{ref}$

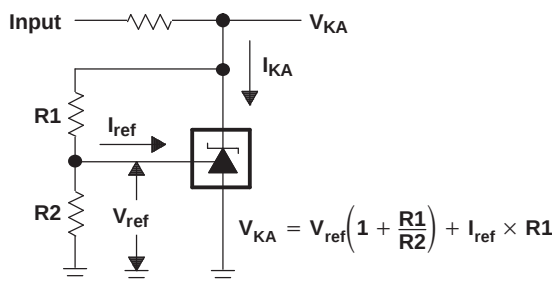


Figure 3. Test Circuit for $V_{KA} > V_{ref}$

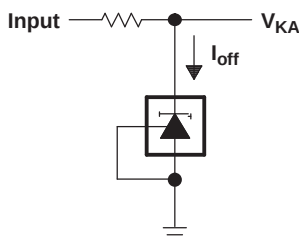


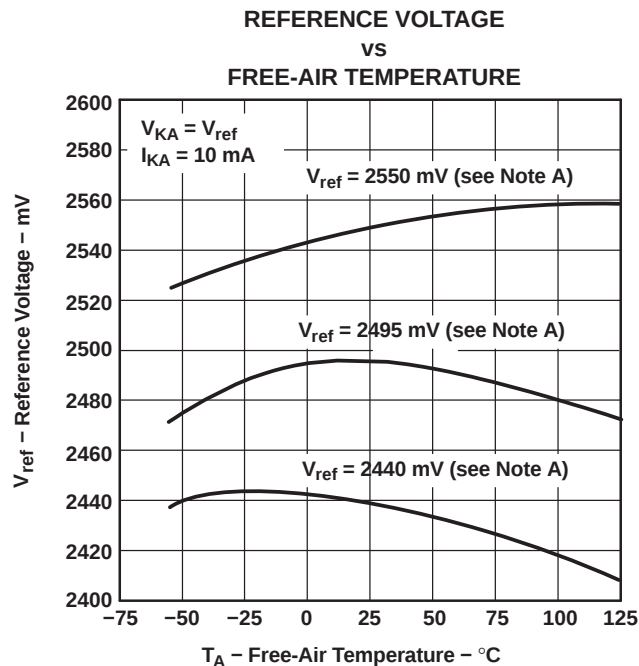
Figure 4. Test Circuit for I_{off}

TYPICAL CHARACTERISTICS

Data at high and low temperatures is applicable only within the recommended operating free-air temperature ranges of the various devices.

Table 1. Graphs

	FIGURE
Reference voltage vs Free-air temperature	Figure 5
Reference current vs Free-air temperature	Figure 6
Cathode current vs Cathode voltage	Figure 7, Figure 8
Off-state cathode current vs Free-air temperature	Figure 9
Ratio of delta reference voltage to delta cathode voltage vs Free-air temperature	Figure 10
Equivalent input noise voltage vs Frequency	Figure 11
Equivalent input noise voltage over a 10-s period	Figure 12
Small-signal voltage amplification vs Frequency	Figure 13
Reference impedance vs Frequency	Figure 14
Pulse response	Figure 15
Stability boundary conditions	Figure 16



A. Data is for devices having the indicated value of V_{ref} at $I_{KA} = 10 \text{ mA}$, $T_A = 25^\circ\text{C}$.

Figure 5.

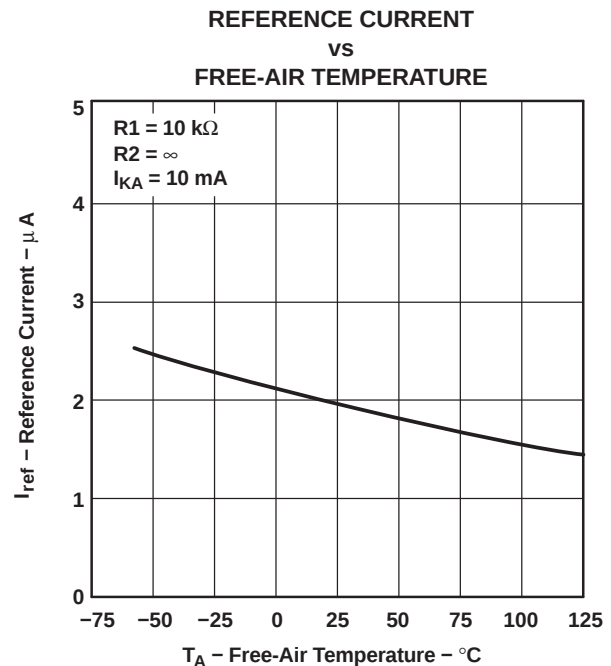


Figure 6.

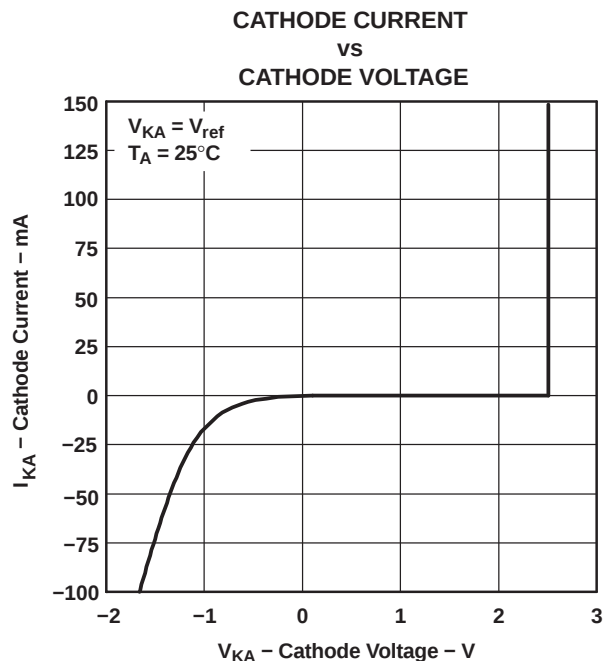


Figure 7.

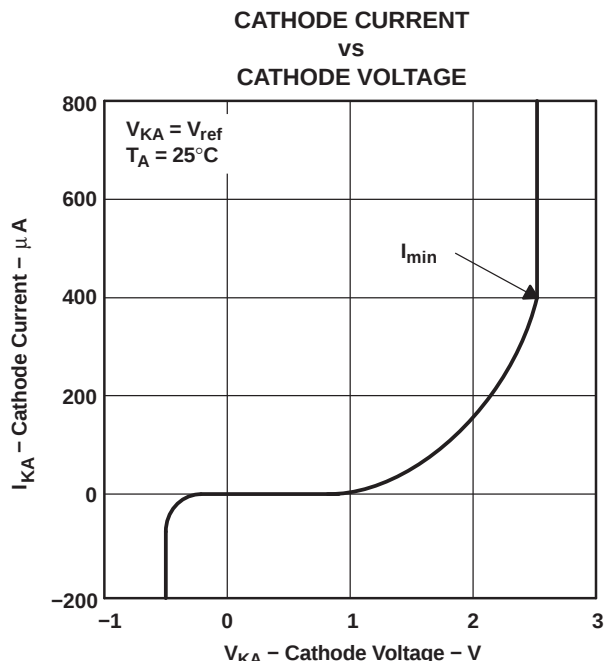


Figure 8.

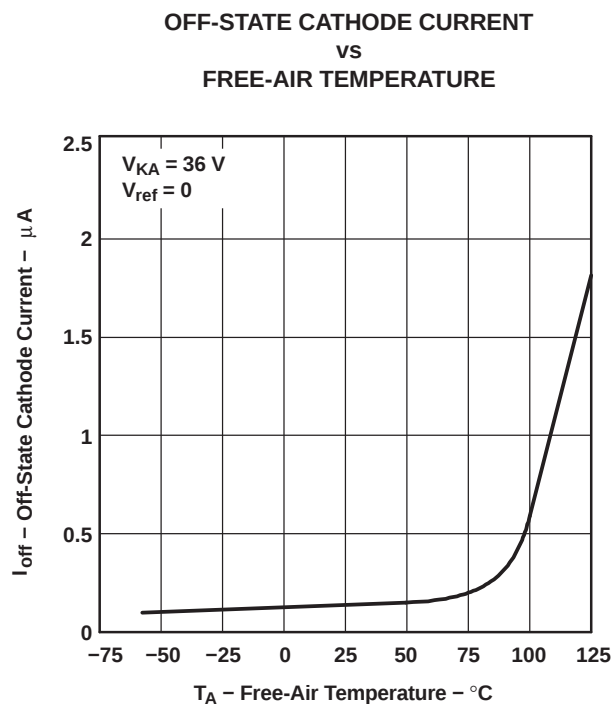


Figure 9.

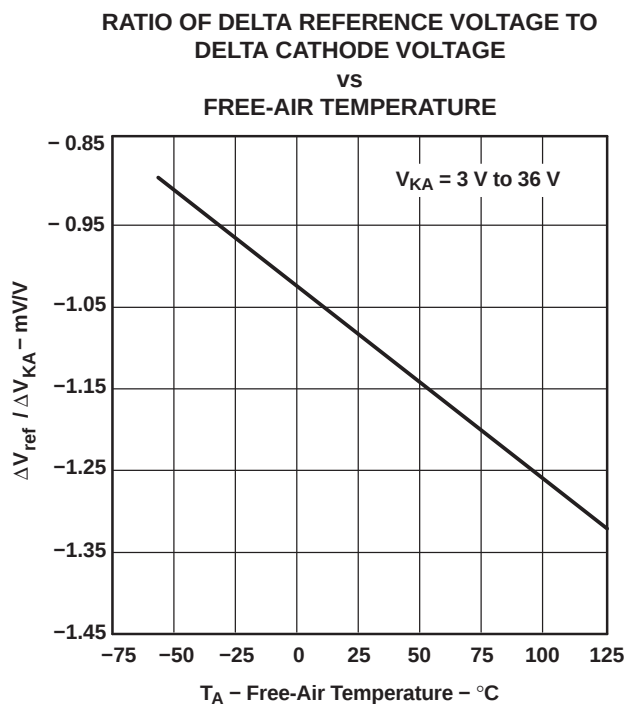


Figure 10.

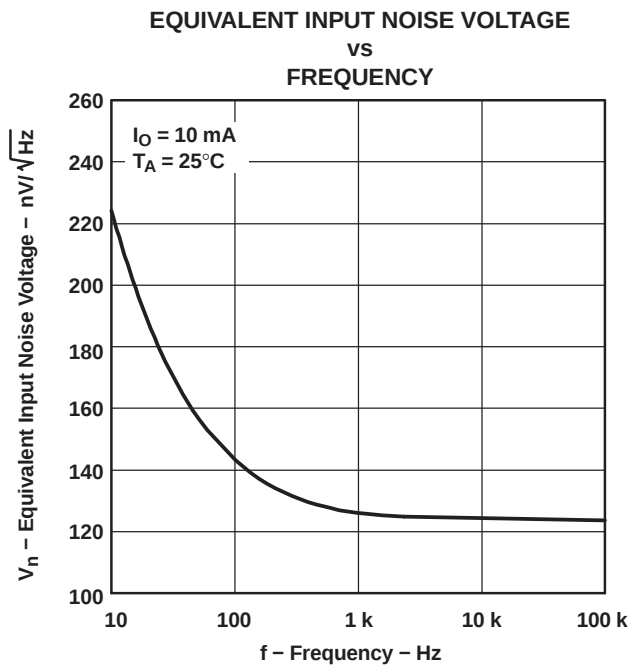


Figure 11.

EQUIVALENT INPUT NOISE VOLTAGE
OVER A 10-S PERIOD

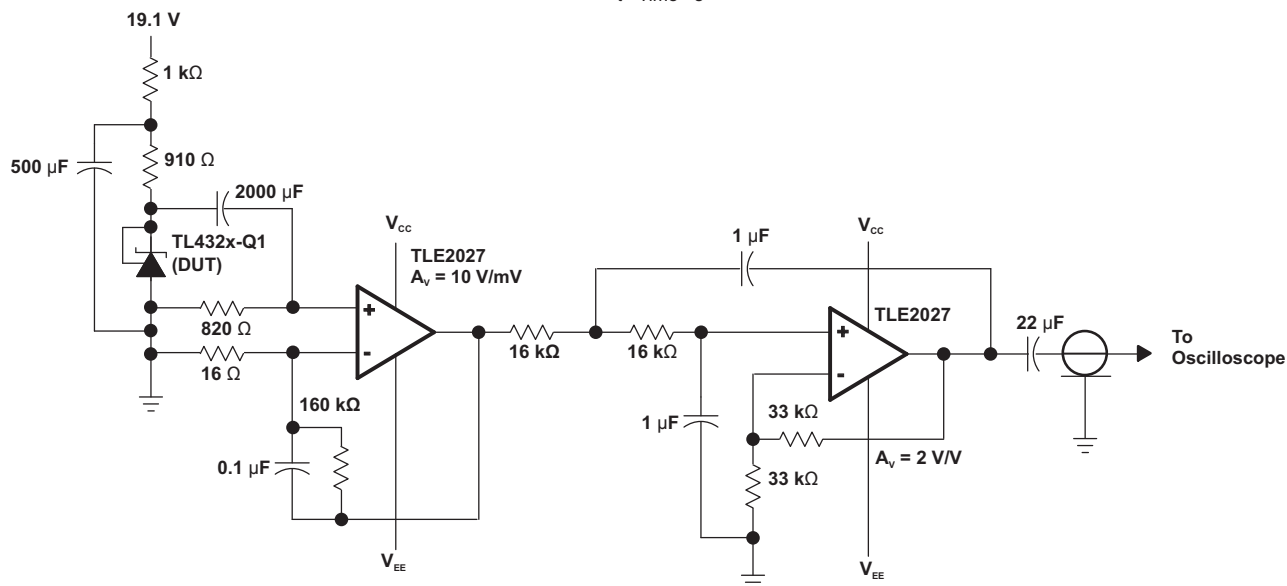
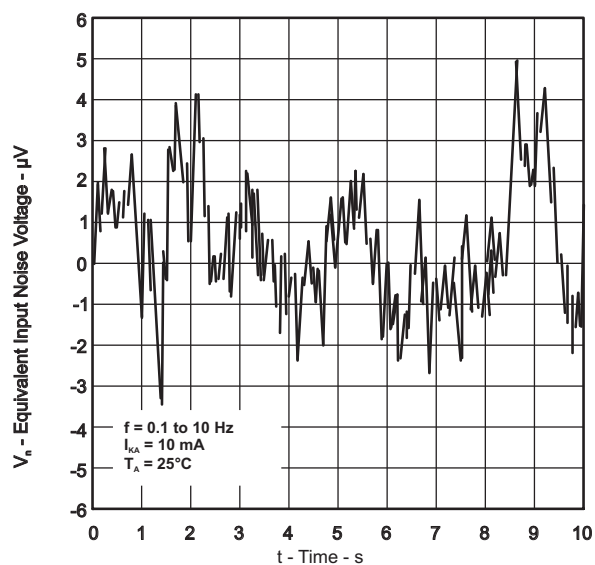


Figure 12. Test Circuit for Equivalent Input Noise Voltage

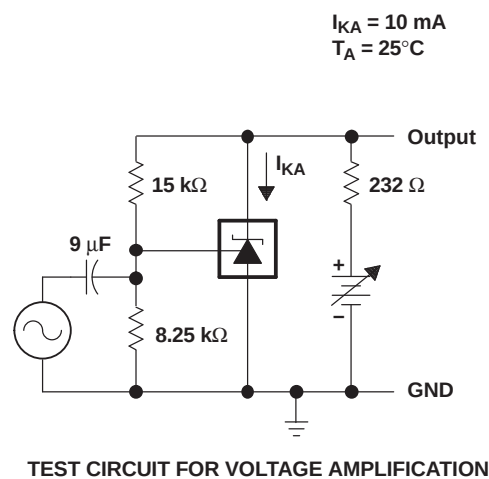
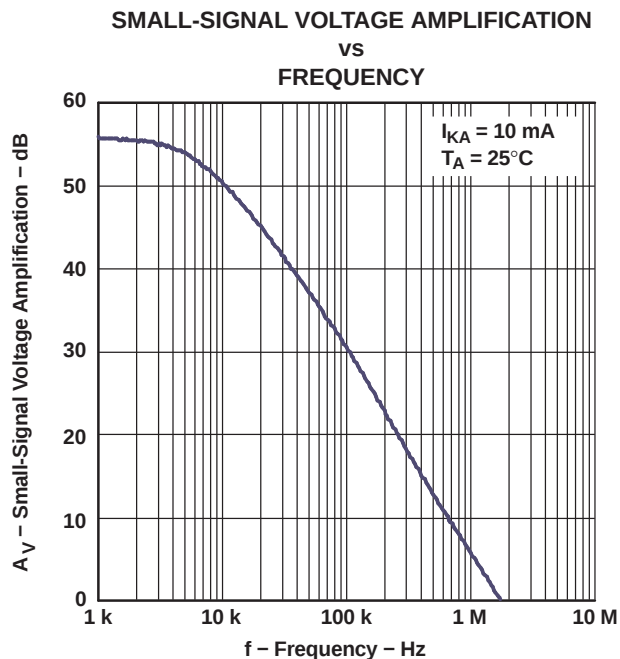


Figure 13.

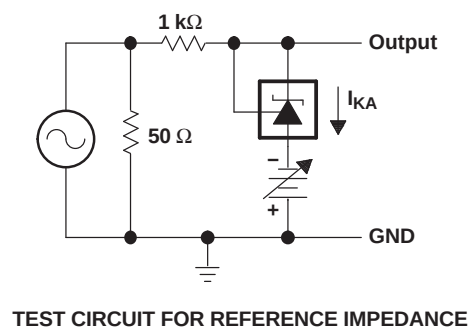
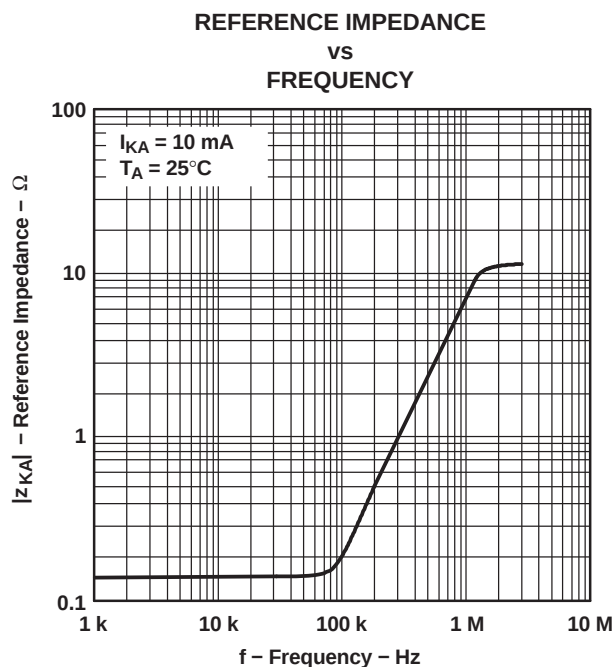


Figure 14.

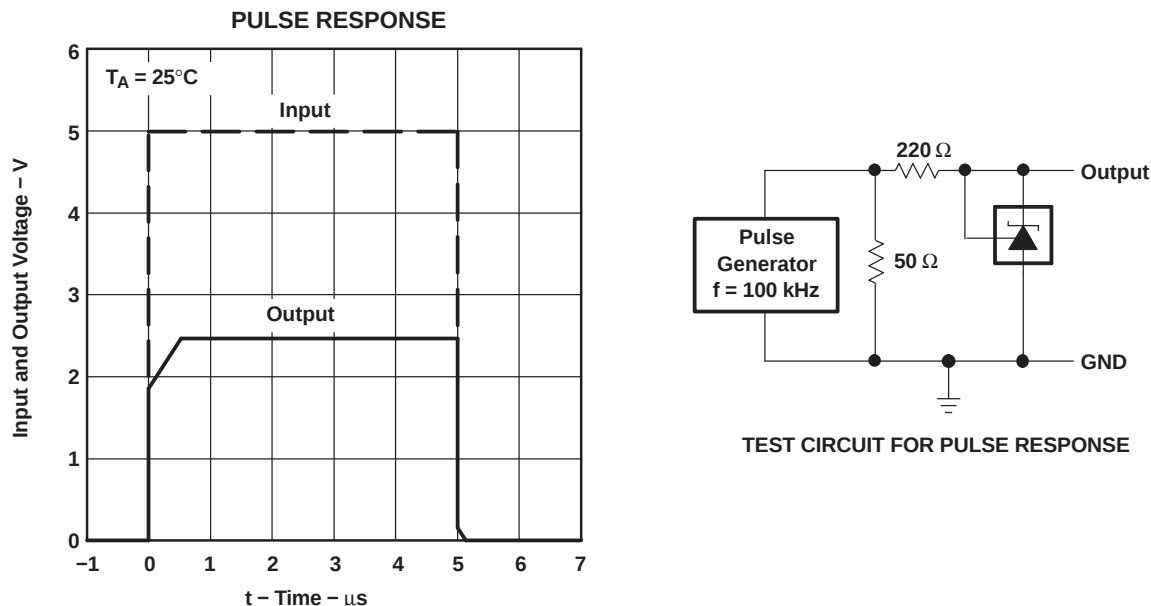


Figure 15.

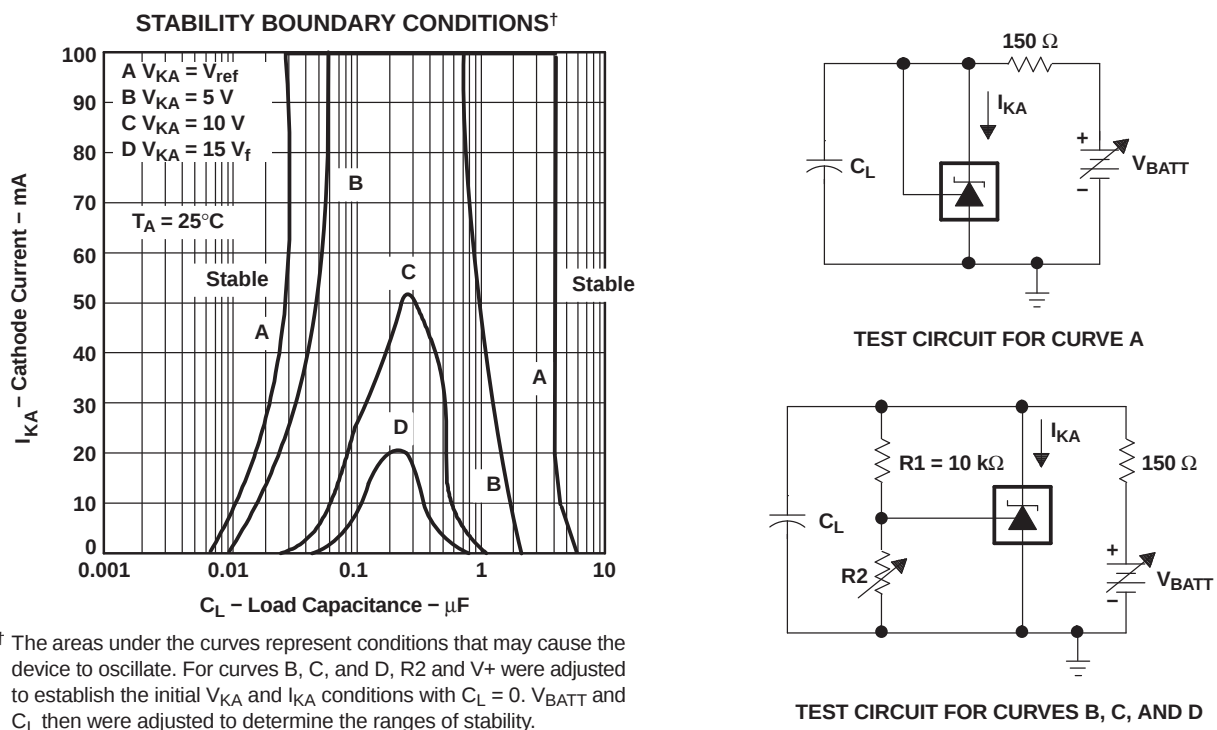
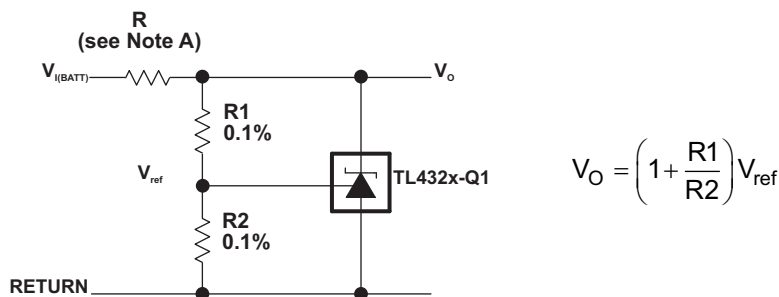


Figure 16.

APPLICATION INFORMATION

Table 2. Application Circuits

	FIGURE
Shunt regulator	Figure 17
Single-supply comparator with temperature-compensated threshold	Figure 18
Precision high-current series regulator	Figure 19
Output control of a three-terminal fixed regulator	Figure 20
High-current shunt regulator	Figure 21
Crowbar circuit	Figure 22
Precision 5-V 1.5-A regulator	Figure 23
Efficient 5-V precision regulator	Figure 24
PWM converter with reference	Figure 25
Voltage monitor	Figure 26
Delay timer	Figure 27
Precision current limiter	Figure 28
Precision constant-current sink	Figure 29



A. R should provide cathode current ≥ 1 mA to the TL432x-Q1 at minimum $V_{I(BATT)}$.

Figure 17. Shunt Regulator

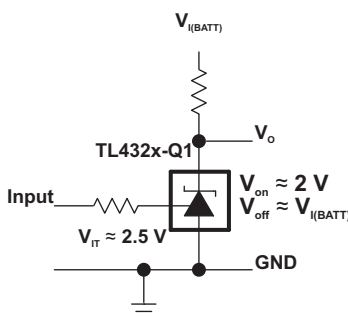
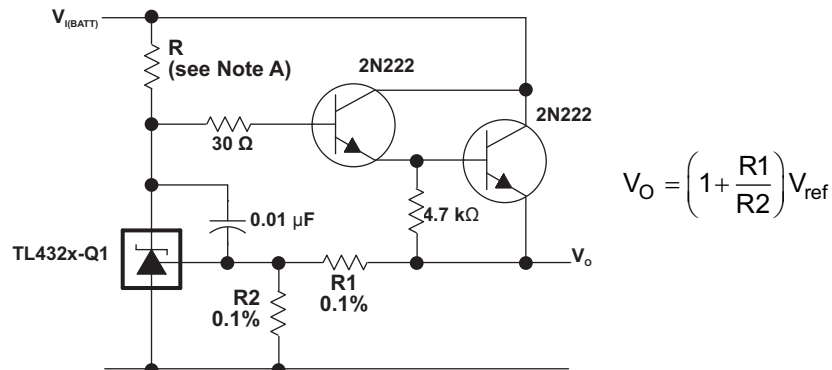


Figure 18. Single-Supply Comparator With Temperature-Compensated Threshold



A. R should provide cathode current ≥ 1 mA to the TL432x-Q1 at minimum $V_{I(BATT)}$.

Figure 19. Precision High-Current Series Regulator

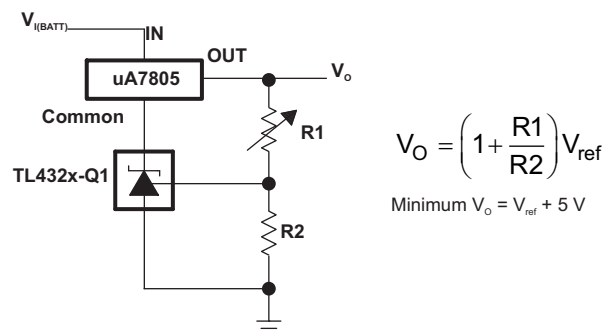


Figure 20. Output Control of a Three-Terminal Fixed Regulator

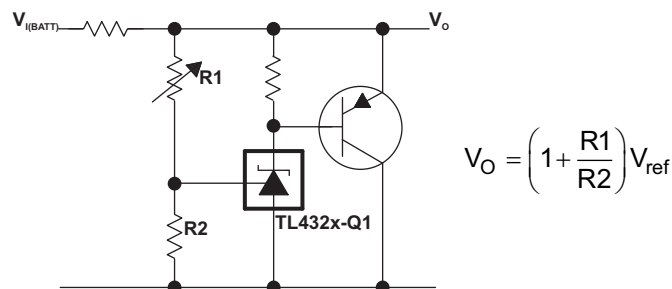
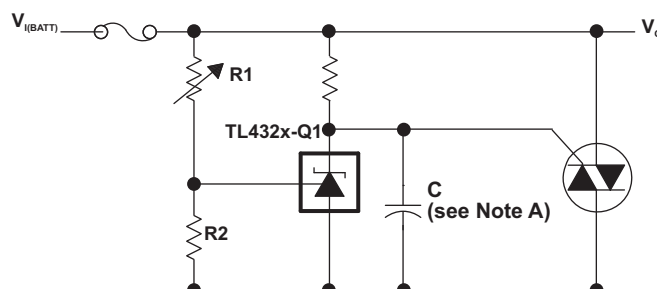


Figure 21. High-Current Shunt Regulator



A. See the stability boundary conditions in [Figure 16](#) to determine allowable values for C.

Figure 22. Crowbar Circuit

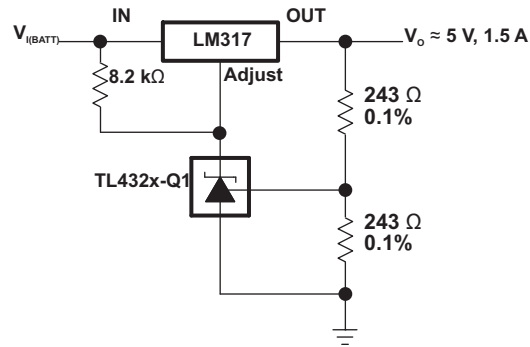
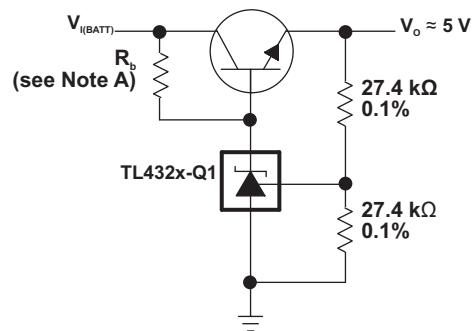


Figure 23. Precision 5-V 1.5-A Regulator



A. R_b should provide cathode current ≥ 1 mA to the TL432x-Q1.

Figure 24. Efficient 5-V Precision Regulator

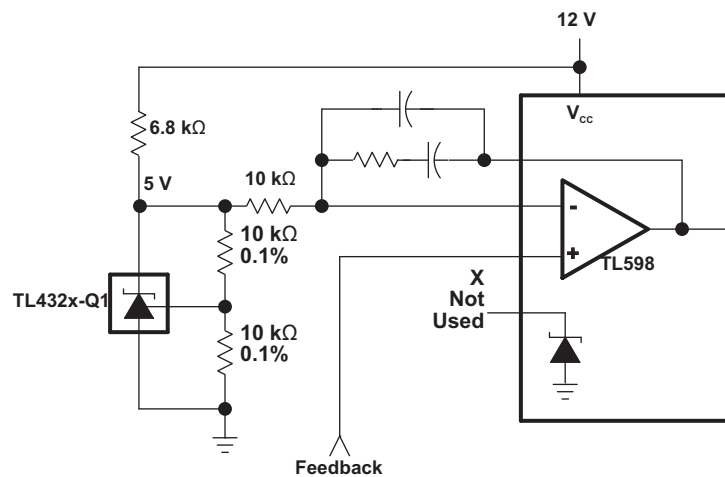
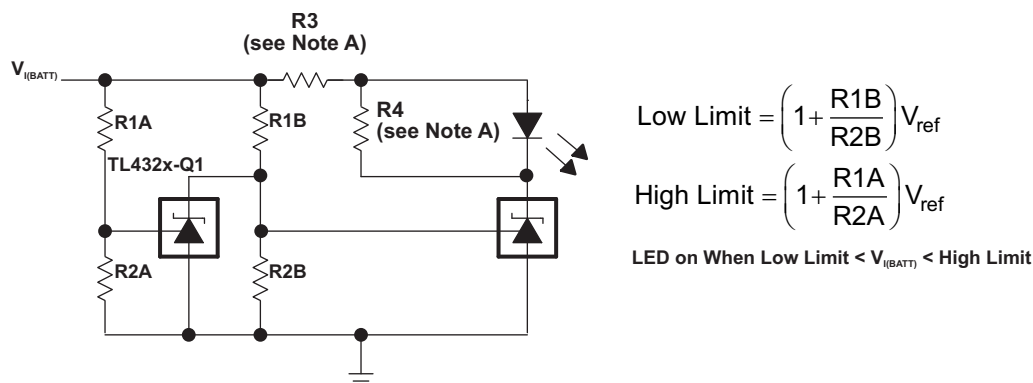


Figure 25. PWM Converter With Reference



- A. R3 and R4 are selected to provide the desired LED intensity and cathode current ≥ 1 mA to the TL432x-Q1 at the available $V_{I(BATT)}$.

Figure 26. Voltage Monitor

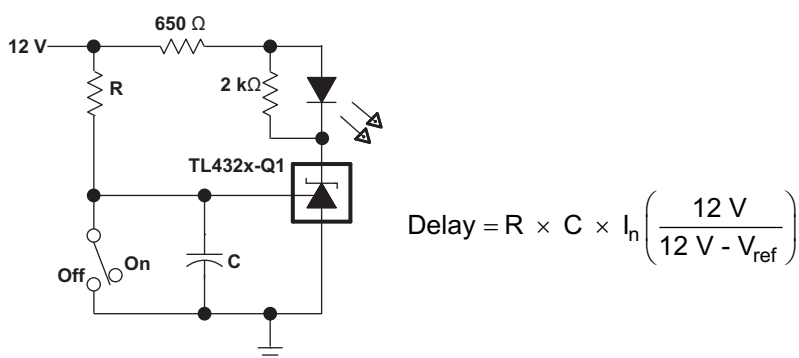


Figure 27. Delay Timer

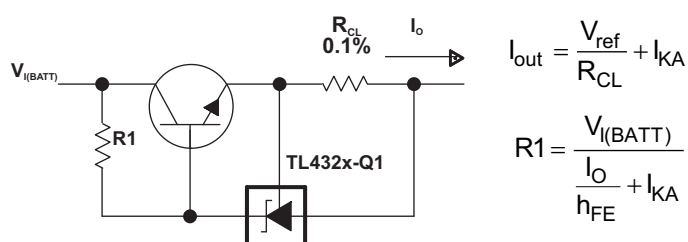


Figure 28. Precision Current Limiter

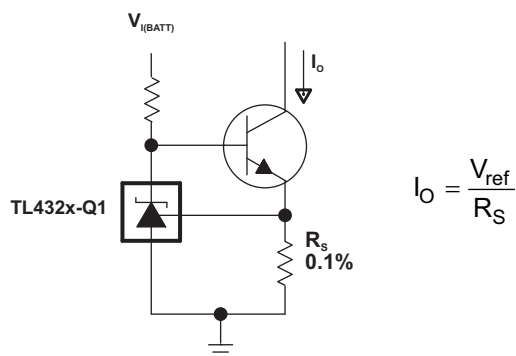


Figure 29. Precision Constant-Current Sink

REVISION HISTORY

Changes from Original (November, 2008) to Revision A	Page
• Added AEC-Q100 info to features	1
• Added ESD ratings information to recommended operating conditions table	3

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TL432AQDBZRQ1	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL432BQDBZRQ1	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TL432A-Q1, TL432B-Q1 :

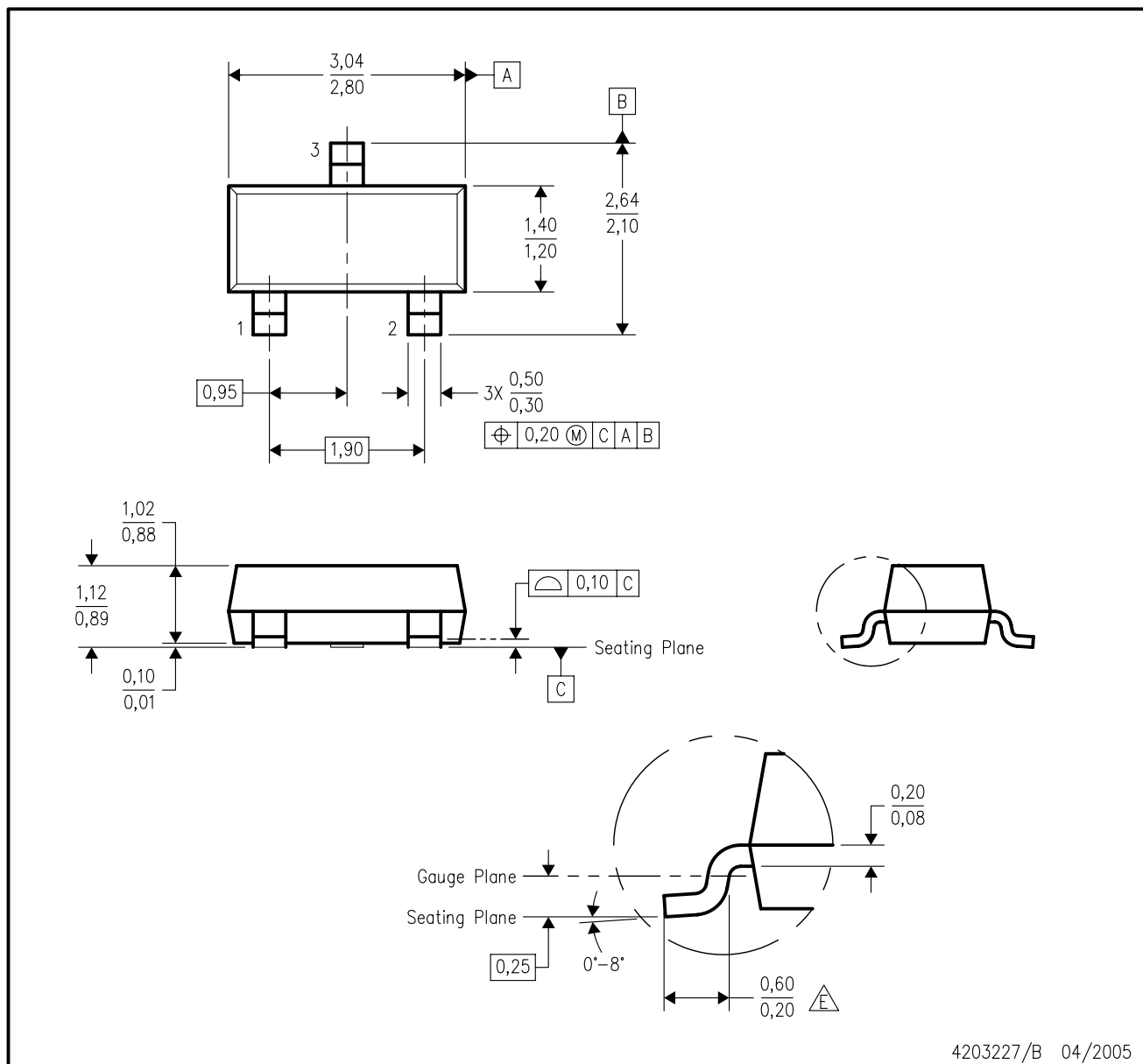
- Catalog: [TL432A](#), [TL432B](#)

NOTE: Qualified Version Definitions:

-
- Catalog - TI's standard catalog product

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



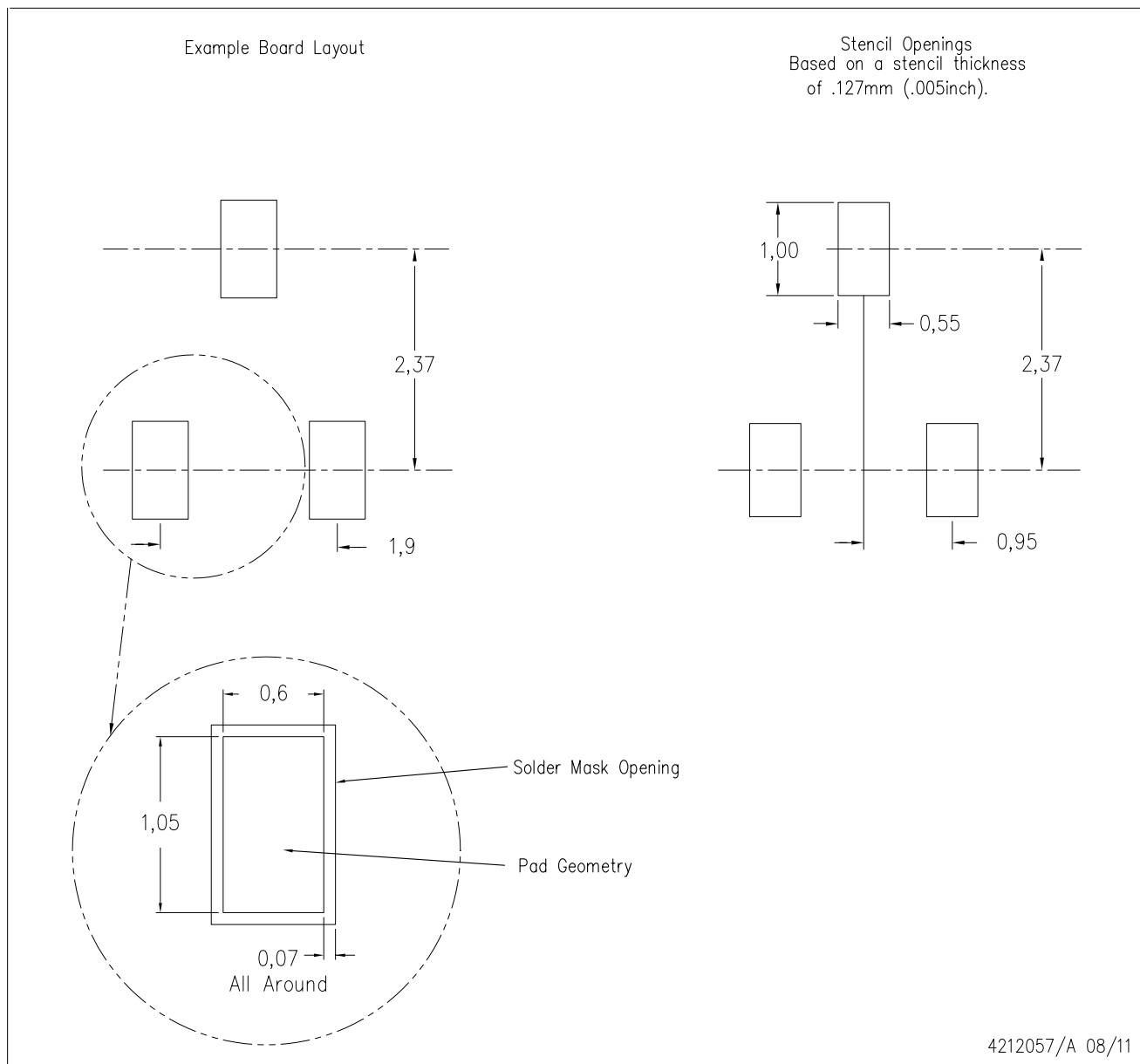
4203227/B 04/2005

NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- E. Falls within JEDEC TO-236 variation AB, except minimum foot length.

DBZ (R-PDSO-G3)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com